

September 24, 2009

CN-092409

Customer Notification M22122G-11 Second Source for Wafer Bump

Dear Valued Customer:

This notification is for the purpose of informing you that our supplier (LSI) has notified Mindspeed that their assembly supplier (Amkor) has added a second qualified source for wafer bumping.

Purpose

Amkor has qualified their China facility, ATC3, as a second source to their Amkor Taiwan existing bumping line. The purpose of the second source is to provide additional capacity.

Product affected

M22122G-11

Change Schedule

Customers may begin to receive product from the alternate test and shipping site beginning on December 23, 2009.

Method to identify parts

Products with wafer bumping at either location are assembled at the same Amkor Korea factory and will therefore have the same marking. Our supplier will maintain records by lot number to indicate where the product was bumped. Product marked with date codes of 0952 or greater may include wafer bumping at either Amkor location.

Customer Impact

No customer impact is anticipated with this change. LSI has successfully completed qualification of product built with wafer bumping at Amkor's ATC3 factory.

We are confident this change will allow Mindspeed Technologies to maintain its high standards for quality and reliability. We will be managing this change very closely to ensure minimum disruption to our customers. If, at any time, you have a need for further information, please contact your local Sales Representative.

Lack of acknowledgement of this PCN within 30 days constitutes acceptance of the change. After acknowledgement, lack of additional response within the 90 day review period constitutes acceptance of the change.

